

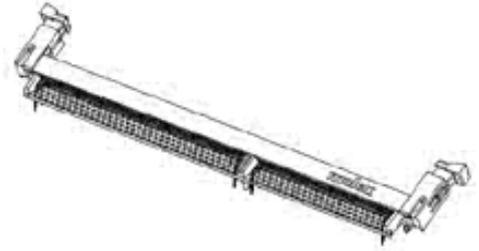
Part Number : [783730001](#)

Product Description : 1.00mm Pitch DDR3 DIMM Socket, 25° Angle, Through Hole, with Beveled Metal Pins, Black Housing and Latches, 0.76µm Gold (Au) Plating, 2.79mm Solder Tail Length, 1.57mm PCB Thickness, 1.5V Center Voltage Key, 240 Circuits

Series Number : 78373

Status : Obsolete

Product Category : Memory Module Connectors



Documents & Resources

[EE-78373-001-001.pdf](#)

[EE-78373-002-001.pdf](#)

[SP-78373-001-001.zip](#)

[SP-78373-002-001.zip](#)

Specifications

[PS-78373-001-001.pdf](#)

Product Environment Compliance

Compliance

GADSL/IMDS	Compliant with Exemption 44; 34; 33
China RoHS	 per SJ/T 11365-2006
EU ELV	Not Relevant
Low-Halogen Status	Not Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2025)4165-DC (25 June 2025)
EU RoHS	Compliant per EU 2015/863

Compliance Statements

- EU RoHS
- REACH SVHC

- Low-Halogen

Industry Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

Substances of Interest

- PFAS

EU RoHS Certificate of Compliance

Additional Product Compliance Information

Part Details

General

Status	Obsolete
Category	Memory Module Connectors
Series	78373
Description	1.00mm Pitch DDR3 DIMM Socket, 25° Angle, Through Hole, with Beveled Metal Pins, Black Housing and Latches, 0.76µm Gold (Au) Plating, 2.79mm Solder Tail Length, 1.57mm PCB Thickness, 1.5V Center Voltage Key, 240 Circuits
Component Type	Socket
JEDEC Outline	MO-269
Product Name	DDR3 DIMM
UPC	883906206697

Agency

CSA	LR19980
UL	E29179

Electrical

Current - Maximum per Contact	1.0A
Voltage Key	Center
Voltage - Maximum	30V AC (RMS)/DC

Physical

Circuits (Loaded)	240
Circuits (maximum)	240
Durability (mating cycles max)	25
Entry Angle	25° Angle
Flammability	94V-0
Housing Color	Black
Keying to Mating Part	Yes
Latch Color	Black
Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	11.547/g
Packaging Type	Tray
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness - Recommended	1.57mm
PC Tail Length	2.79mm
Pitch - Mating Interface	1.00mm
Pitch - Termination Interface	1.00mm
Plating min - Mating	0.762µm
Plating min - Termination	2.540µm
Temperature Range - Operating	-55° to +85°C
Termination Interface Style	Through Hole

Solder Process Data

Max-Duration	10
Lead-Free Process Capability	SMC&WAVE
Max-Cycle	2
Max-Temp	260

Mates With / Use With

Mates with Part(s)

Description	Part Number
Mates With	JEDEC Standard 1.27mm Modules

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Obsolete